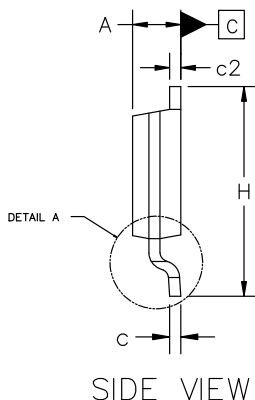
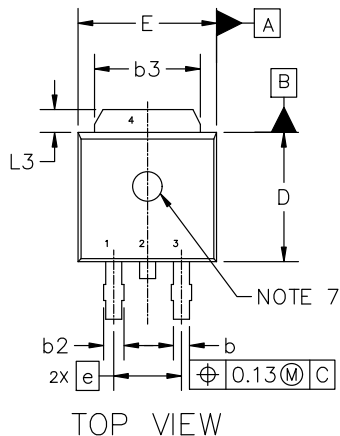


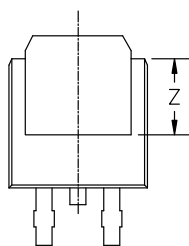
DPAK-3 6.10x6.54x2.28, 2.29P
CASE 369C
ISSUE K

DATE 14 MAY 2026

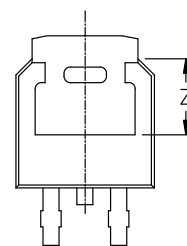
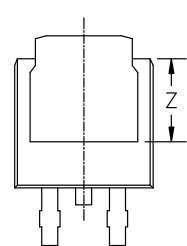
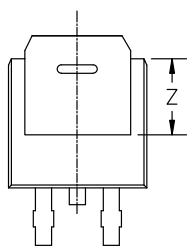
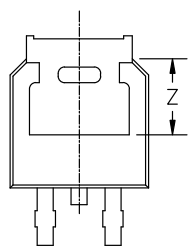
SCALE 1:1



MILLIMETERS			
DIM	MIN	NOM	MAX
A	2.18	2.28	2.38
A1	0.00	---	0.13
b	0.63	0.76	0.89
b2	0.72	0.93	1.14
b3	4.57	5.02	5.46
c	0.46	0.54	0.61
c2	0.46	0.54	0.61
D	5.97	6.10	6.22
E	6.35	6.54	6.73
e	2.29 BSC		
H	9.40	9.91	10.41
L	1.40	1.59	1.78
L1	2.90 REF		
L2	0.51 BSC		
L3	0.89	---	1.27
L4	---	---	1.01
Z	3.93	---	---



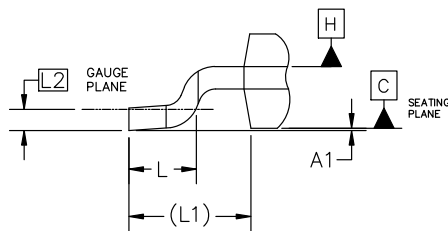
BOTTOM VIEW



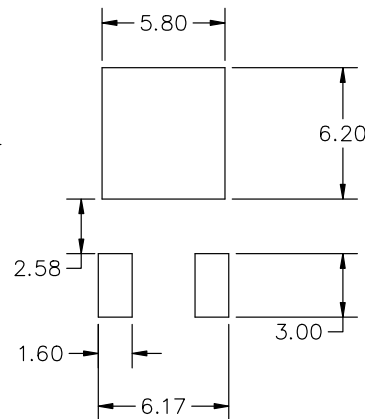
ALTERNATE CONSTRUCTIONS

NOTES:

1. DIMENSIONING AND TOLERANCING ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.



DETAIL A
ROTATED 90° CW



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

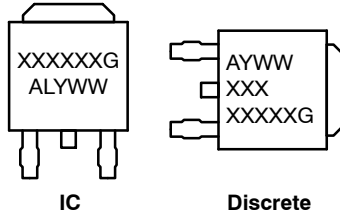
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DPAK-3 6.10x6.54x2.28, 2.29P
CASE 369C
ISSUE K

DATE 13 MAY 2026

**GENERIC
MARKING DIAGRAM***



- XXXXXX = Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

- | | | | | |
|--|--|---|---|--|
| <p>STYLE 1:
 PIN 1. BASE
 2. COLLECTOR
 3. EMITTER
 4. COLLECTOR</p> | <p>STYLE 2:
 PIN 1. GATE
 2. DRAIN
 3. SOURCE
 4. DRAIN</p> | <p>STYLE 3:
 PIN 1. ANODE
 2. CATHODE
 3. ANODE
 4. CATHODE</p> | <p>STYLE 4:
 PIN 1. CATHODE
 2. ANODE
 3. GATE
 4. ANODE</p> | <p>STYLE 5:
 PIN 1. GATE
 2. ANODE
 3. CATHODE
 4. ANODE</p> |
| <p>STYLE 6:
 PIN 1. MT1
 2. MT2
 3. GATE
 4. MT2</p> | <p>STYLE 7:
 PIN 1. GATE
 2. COLLECTOR
 3. EMITTER
 4. COLLECTOR</p> | <p>STYLE 8:
 PIN 1. N/C
 2. CATHODE
 3. ANODE
 4. CATHODE</p> | <p>STYLE 9:
 PIN 1. ANODE
 2. CATHODE
 3. RESISTOR ADJUST
 4. CATHODE</p> | <p>STYLE 10:
 PIN 1. CATHODE
 2. ANODE
 3. CATHODE
 4. ANODE</p> |

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